

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Please amend the claims as shown in the following listing:

1. (Original) An epoxy resin composition for packaging a semiconductor element, obtained by formulating:

(A) phenol aralkyl type of epoxy resin having a biphenylene unit in the main chain;

(B) a phenolic resin;

(C) a curing accelerator;

(D) an inorganic filler; and

(E) an oxidized polyethylene wax having a drop point within a range of from 60 to 140 degree C, an acid value within a range of from 10 to 100 (mg KOH/g), a number average molecular weight within a range of from 500 to 20,000, and a mean particle size within a range of from 5 to 100 μm .

2. (Original) An epoxy resin composition for packaging a semiconductor element, obtained by formulating:

(A) an epoxy resin;

(B) a phenol aralkyl type of phenolic resin having a biphenylene unit in the main chain;

(C) a curing accelerator;

(D) an inorganic filler; and

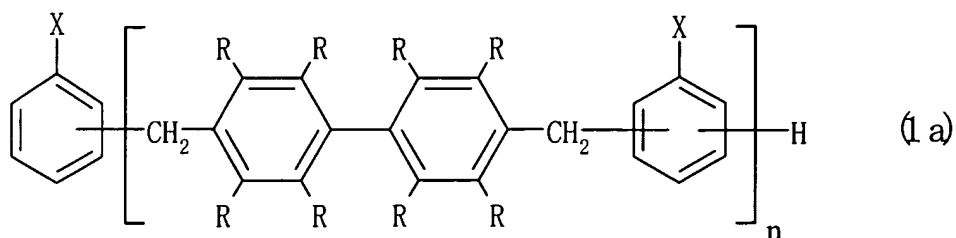
(E) an oxidized polyethylene wax having a drop point within a range of from 60 to 140 degree C, an acid value within a range of from 10 to 100 (mg KOH/g), a number average molecular weight within a range of from 500 to 20,000, and a mean particle size within a range of from 5 to 100 μm .

3. (Original) The epoxy resin composition for packaging a semiconductor element, according to claim 2,

wherein the said (A) epoxy is a phenol aralkyl type of epoxy resin having a biphenylene unit in the main chain.

4. (Currently Amended) The epoxy resin composition for packaging a semiconductor element, according to claim 1,

wherein the said (A) epoxy resin has a structure represented by general formula (1a):

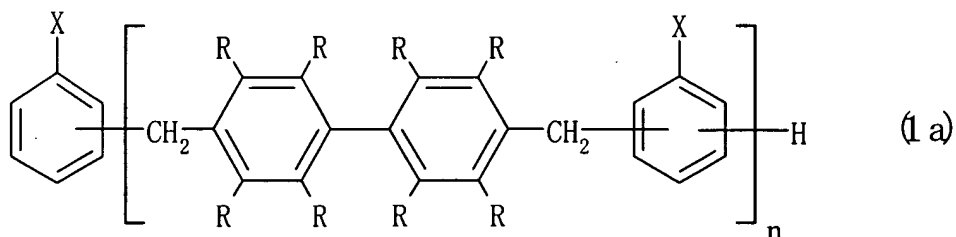


~~(wherein, Rs, each of which~~ wherein R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.[])

5. (Currently Amended) The epoxy resin composition for packaging a semiconductor element, according to claim 2,

wherein the said (A) epoxy resin has a structure represented by general formula

(1a):

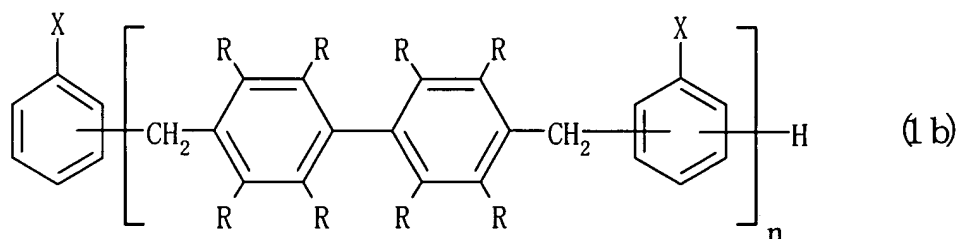


~~(wherein, Rs, each of which~~ wherein R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.[])

6. (Currently Amended) The epoxy resin composition for packaging a semiconductor element, according to claim 1,

wherein the said (B) phenolic resin has a structure represented by general formula

(1b):

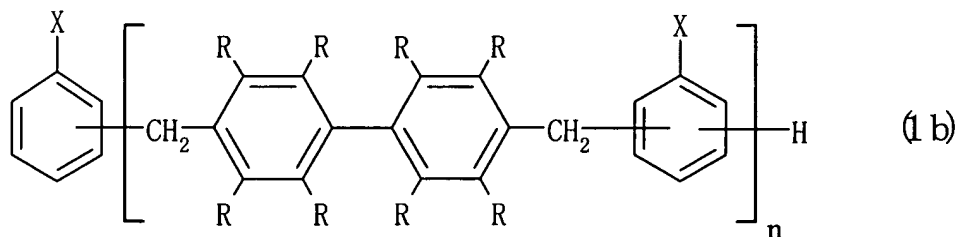


~~(wherein Rs, each of which~~ wherein R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.[)]

7. (Currently Amended) The epoxy resin composition for packaging a semiconductor element, according to claim 2,

wherein the said (B) phenolic resin has a structure represented by general formula

(1b):



~~wherein, Rs, each of which~~ wherein R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.[)]

8. (Original) The epoxy resin composition for packaging a semiconductor element, according to claim 1,

wherein content of said (E) oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

9. (Original) The epoxy resin composition for packaging a semiconductor element, according to claim 2,

wherein content of said (E) oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

10. (Original) A semiconductor device, which is formed by employing said epoxy resin composition according to claim 1 to package a semiconductor element included therein.

11. (Original) A semiconductor device, which is formed by employing said epoxy resin composition according to claim 2 to package a semiconductor element included therein.

12. (New) A moldable epoxy resin composition for packaging a semiconductor element, comprising:

phenol aralkyl type of epoxy resin having a biphenylene unit in the main chain;

a phenolic resin;

an inorganic filler; and

an oxidized polyethylene wax having a drop point within a range of from 60 to 140 degree C, an acid value within a range of from 10 to 100 (mg KOH/g), a number average molecular weight within a range of from 500 to 20,000, and a mean particle size within a range of from 5 to 100 μm .

13. (New) A moldable epoxy resin composition for packaging a semiconductor element, comprising:

an epoxy resin;

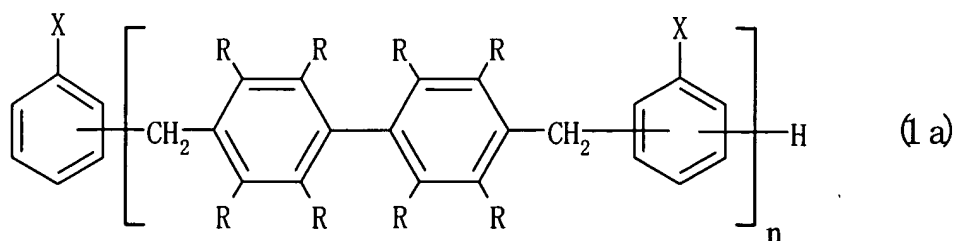
a phenol aralkyl type of phenolic resin having a biphenylene unit in the main chain;

an inorganic filler; and

an oxidized polyethylene wax having a drop point within a range of from 60 to 140 degree C, an acid value within a range of from 10 to 100 (mg KOH/g), a number average molecular weight within a range of from 500 to 20,000, and a mean particle size within a range of from 5 to 100 μm .

14. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 12,

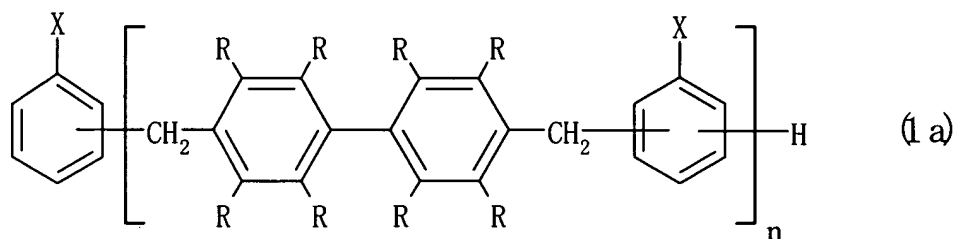
wherein the said epoxy resin has a structure represented by general formula (1a):



wherein, R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.

15. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 13,

wherein the said epoxy resin has a structure represented by general formula (1a):

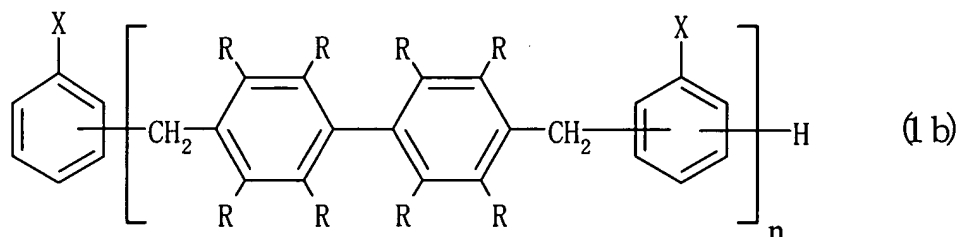


wherein, R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents glycidyl ether group; and n represents a positive number more than or equal to 1.

16. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 12,

wherein the said phenolic resin has a structure represented by general formula

(1b):

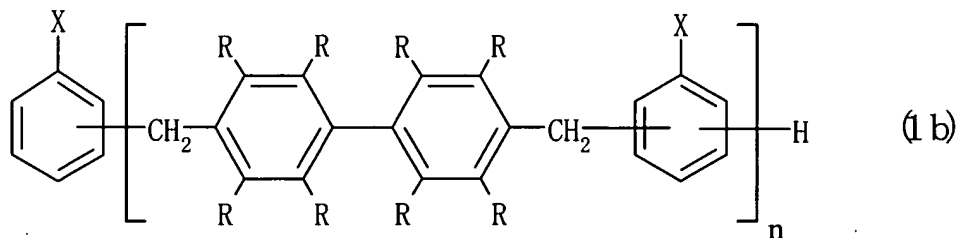


wherein, R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.

17. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 13,

wherein the said phenolic resin has a structure represented by general formula

(1b):



wherein, R may be same or different, and represents a hydrogen atom or functional group selected from alkyl groups having 1 carbon to 4 carbons; X represents hydroxyl group; and n represents a positive number more than or equal to 1.

18. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 12,

wherein the content of said oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

19. (New) The moldable epoxy resin composition for packaging a semiconductor element, according to claim 13,

wherein the content of said oxidized polyethylene wax in said epoxy resin composition is within a range of from 0.01 to 1 % wt.

20. (New) A composition for encapsulating a semiconductor device, comprising:

- (1) the moldable epoxy resin composition according to claim 12, and
- (2) a curing accelerator.

21. (New) A composition for encapsulating a semiconductor device, comprising:

- (1) the moldable epoxy resin composition according to claim 13, and
- (2) a curing accelerator.